

# **600V Super-Junction Power MOSFET**

#### **FEATURES**

- $\bullet \quad \text{Very low FOM R}_{\text{DS(on)}} \times \text{Q}_{\text{g}} \\$
- 100% avalanche tested
- RoHS compliant

#### **APPLICATIONS**

- Switch Mode Power Supply (SMPS)
- Uninterruptible Power Supply (UPS)
- Power Factor Correction (PFC)



Device Marking and Package Information				
Device	TPA60R2K5C	TPP60R2K5C	TPU60R2K5C	TPD60R2K5C
Package	TO-220F	TO-220	TO-251	TO-252
Marking	60R2K5C	60R2K5C	60R2K5C	60R2K5C

<b>Absolute Maximum Ratings</b> $T_C = 25^{\circ}C$ , unless otherwise noted					
Parameter		Cumbal	Value		Unit
		Symbol	TO-220,TO-251,TO-252	TO-220F	Unit
Drain-Source Voltage (V <sub>GS</sub> = 0V)		$V_{\rm DSS}$	600		٧
Continuous Drain Current		$I_D$	1.6		Α
Pulsed Drain Current (no	ote1)	I <sub>DM</sub>	4.8		Α
Gate-Source Voltage		$V_{\rm GSS}$	±30		>
Single Pulse Avalanche Energy (no	ote2)	E <sub>AS</sub>	1.25		mJ
Avalanche Current (no	ote1)	I <sub>AR</sub>	0.5		Α
Repetitive Avalanche Energy (no	ote1)	$E_AR$	0.04		mJ
Power Dissipation (T <sub>C</sub> = 25°C)		$P_{D}$	16.7	8.1	W
Operating Junction and Storage Temperature Range		$T_J,T_stg$	-55~+150		°C

Thermal Resistance				
Parameter	Symbol	Value		Unit
Parameter	Symbol	TO-220,TO-251,TO-252	TO-220F	Onit
Thermal Resistance, Junction-to-Case	R <sub>thJC</sub>	7.5	15.4	12/\\\
Thermal Resistance, Junction-to-Ambient	R <sub>thJA</sub>	62	80	K/W

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### TPA60R2K5C,TPP60R2K5C,TPU60R2K5C,TPD60R2K5C

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Specifications T <sub>J</sub> = 25°C, unless otherwise noted  Value						
Parameter	rameter Symbol Test Conditions		Min. Typ. Max.		Unit	
Static				Į.	!	
Drain-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	$V_{GS} = 0V, I_{D} = 250\mu A$	600			V
7. 0 / 1/1   5 / 0 /		$V_{DS} = 600V, V_{GS} = 0V, T_{J} = 25^{\circ}C$			1	
Zero Gate Voltage Drain Current	$I_{DSS}$ $V_{DS} = 600 \text{V}, V_{GS} = 0 \text{V}, T_{J} = 150 ^{\circ}\text{C}$			100	μΑ	
Gate-Source Leakage	I <sub>GSS</sub>	$V_{GS} = \pm 30V$			±100	nA
Gate-Source Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	2.5		4.0	V
Drain-Source On-Resistance (Note3)	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10V, I <sub>D</sub> = 0.8A		2.0	2.5	Ω
Forward Transconductance (Note3)	g <sub>fs</sub>	$V_{DS} = 10V, I_{D} = 0.8A$		1.4		S
Dynamic		•				
Input Capacitance	C <sub>iss</sub>	V 0V		147		
Output Capacitance	C <sub>oss</sub>	$V_{GS} = 0V,$ $V_{DS} = 50V,$		27		pF
Reverse Transfer Capacitance	C <sub>rss</sub>	f = 1.0MHz		5		
Total Gate Charge	$Q_g$			4.4		
Gate-Source Charge	$Q_{gs}$	$V_{DD} = 480V, I_{D} = 1.6A, V_{GS} = 10V$		0.7		nC
Gate-Drain Charge	$Q_{gd}$	63		2.5		
Turn-on Delay Time	t <sub>d(on)</sub>			48		
Turn-on Rise Time	t <sub>r</sub>	$V_{DD} = 400V, I_{D} = 1.6A,$		16		
Turn-off Delay Time	t <sub>d(off)</sub>	$R_G = 25\Omega$		32		ns
Turn-off Fall Time	t <sub>f</sub>			22		
Drain-Source Body Diode Characteris	stics					
Continuous Body Diode Current	I <sub>S</sub>	T _ 250C			1.6	
Pulsed Diode Forward Current	I <sub>SM</sub>	T <sub>C</sub> = 25°C			6.4	Α
Body Diode Voltage	V <sub>SD</sub>	$T_J = 25^{\circ}C$ , $I_{SD} = 1.6A$ , $V_{GS} = 0V$		0.9	1.2	V
Reverse Recovery Time	t <sub>rr</sub>			104		ns
Reverse Recovery Charge	Q <sub>rr</sub>	$V_R = 400V, I_F = I_S, di_F/dt = 100A/\mu s$		0.4		μC
Peak Reverse Recovery Current	I <sub>rrm</sub>			4.1		Α

#### **Notes**

- 1. Repetitive Rating: Pulse Width limited by maximum junction temperature
- 2.  $I_{AS}$  = 0.5A,  $V_{DD}$  = 50V,  $R_{G}$  = 25 $\Omega$ , Starting  $T_{J}$  = 25°C
- 3. Pulse Test: Pulse Width ≤ 300µs, Duty Cycle ≤ 1%





6

5

2

0

0

I<sub>D</sub>, Drain Current (A)

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### **Typical Characteristics** $T_J = 25^{\circ}C$ , unless otherwise noted

Figure 1. Output Characteristics 20V 10V 6V 5.5V 5V 4.5V

Figure 3. On-Resistance vs. Drain Current

10

V<sub>DS</sub>, Drain-to-Source Voltage (V)

15

20

5

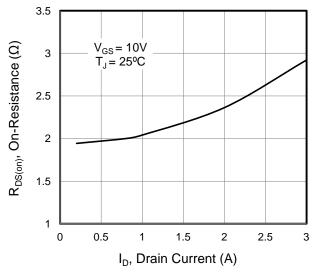


Figure 5. Gate Charge

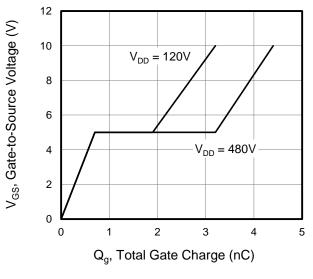


Figure 2. Transfer Characteristics

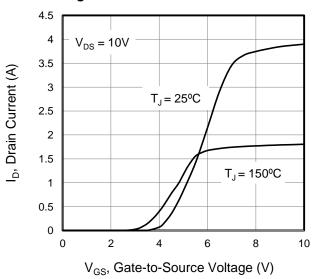


Figure 4. Capacitance

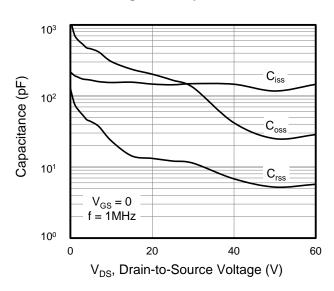
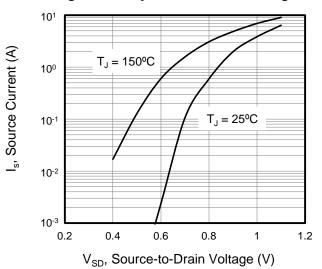


Figure 6. Body Diode Forward Voltage



### **Typical Characteristics** $T_J = 25^{\circ}$ C, unless otherwise noted

Figure 7. On-Resistance vs. Junction Temperature

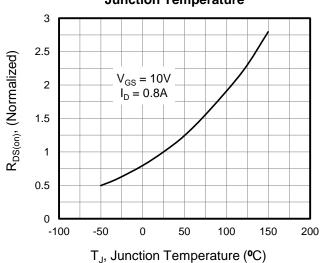


Figure 9. Transient Thermal Impedance TO-220/TO-251/TO-252

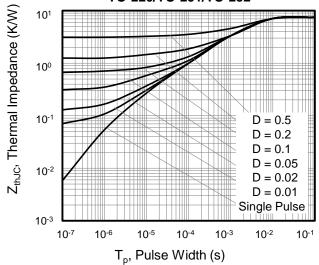
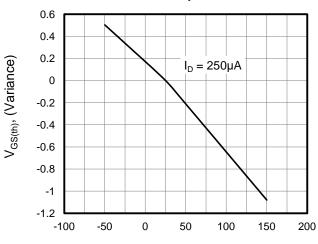
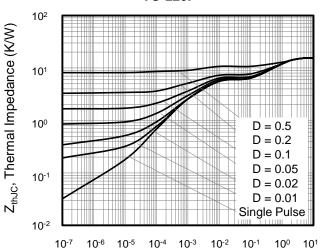


Figure 8. Threshold Voltage vs. Junction Temperature



T<sub>J</sub>, Junction Temperature (°C)

Figure 10. Transient Thermal Impedance TO-220F



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Figure A: Gate Charge Test Circuit and Waveform

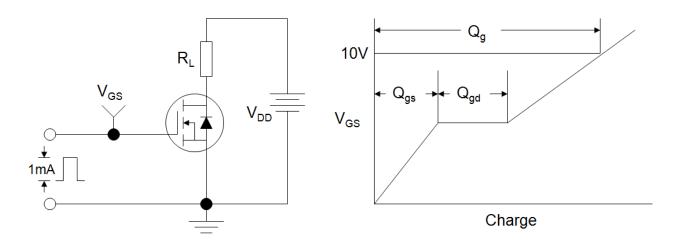


Figure B: Resistive Switching Test Circuit and Waveform

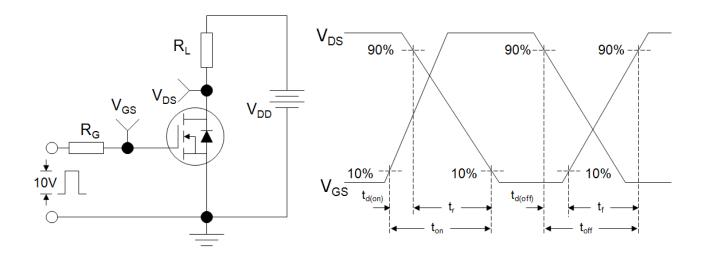
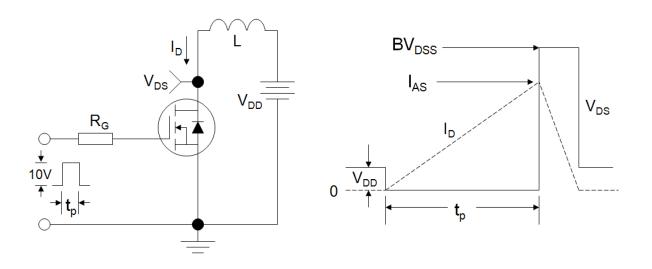


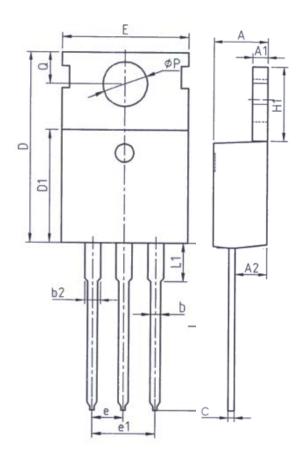
Figure C: Unclamped Inductive Switching Test Circuit and Waveform

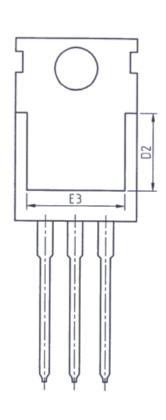


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# **TO-220**

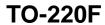


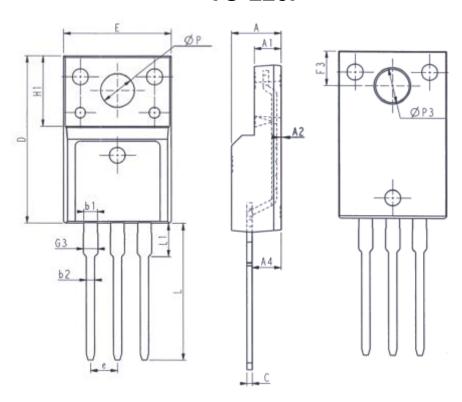


Unit: mm				
Symbol	Min.	Max.		
Α	4. 37	4. 77		
A1	1. 25	1. 45		
A2	2. 20	2. 60		
b	0. 70	0. 95		
b2	1. 17	1. 47		
С	0. 40	0. 65		
D	15. 10	16. 10		
D1	8. 80	9. 40		
D2	5. 50	_		

Unit: mm			
Symbol	Min.	Max.	
E	9. 70	10.30	
E3	7. 00	-	
е	2. 54BSC		
e1	5. 08	BBSC	
H1	6. 25	6. 85	
L	12. 75	13.80	
L1	-	3. 40	
Р	3. 40	3. 80	
Q	2. 60	3. 00	



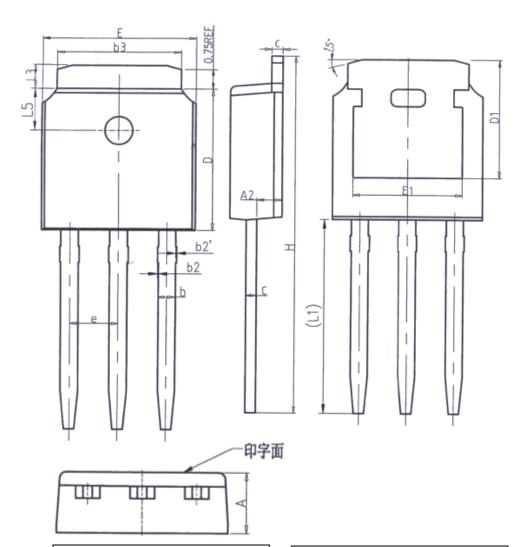




l	Unit: mm		Unit: mm		
Symbol	Min.	Max.	Symbol	Min.	Max.
E	9. 96	10. 36	L	12. 68	13. 28
Α	4. 50	4. 90	L1	2. 93	3. 13
<b>A</b> 1	2. 34	2. 74	Р	3. 03	3. 38
A2	0.30	0. 60	Р3	3. 15	3. 65
A4	2. 56	2. 96	F3	3. 15	3. 45
С	0. 40	0. 65	G3	1. 25	1. 55
D	15. 57	16. 17	b1	1. 18	1. 43
H1	6. 70REF		b2	0. 70	0. 95
e	2. 54BSC				



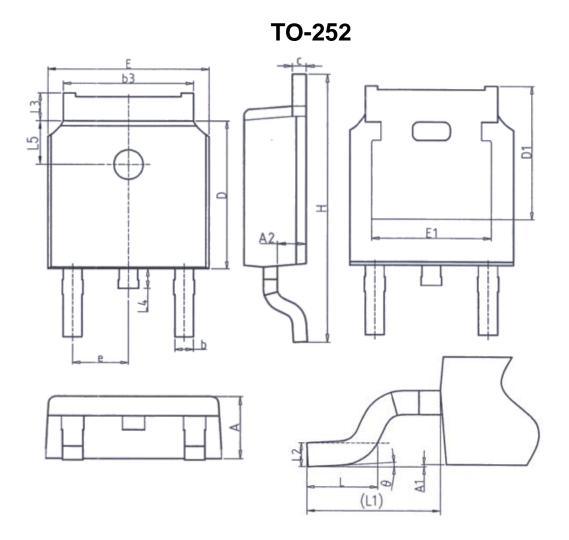
# **TO-251**



Unit: mm			
Symbol	Min.	Max.	
Α	2. 20	2. 40	
A2	0. 97	1. 17	
b	0. 68	0. 90	
b2	0.00	0.10	
b2′	0.00	0.10	
b3	5. 20	5. 50	
С	0. 43	0. 63	
D	5. 98	6. 22	

Unit: mm			
Symbol	Min.	Max.	
D1	5. 30	REF	
E	6. 40	6. 80	
E1	4. 63	-	
е	2. 286BSC		
Н	16. 22	16. 82	
L1	9. 15	9. 65	
L3	0.88	1. 28	
L5	1. 65	1. 95	





Unit: mm				
Symbol	Min.	Max.		
Α	2. 20	2. 40		
A1	0.00	0. 20		
A2	0. 97	1. 17		
b	0. 68	0. 90		
b3	5. 20	5. 50		
С	0. 43	0. 63		
D	5. 98	6. 22		
D1	D1 5. 30REF			
E	6. 40	6. 80		
E1	4. 63	-		

Unit: mm			
Symbol	Min.	Max.	
е	2. 28	6BSC	
Н	9. 40	10.50	
L	1. 38	1. 75	
L1	2. 90REF		
L2	0. 51	IBSC	
L3	0.88	1. 28	
L4	_	1.00	
L5	1. 65	1. 95	
θ	0°	8°	

#### TPA60R2K5C,TPP60R2K5C,TPU60R2K5C,TPD60R2K5C



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